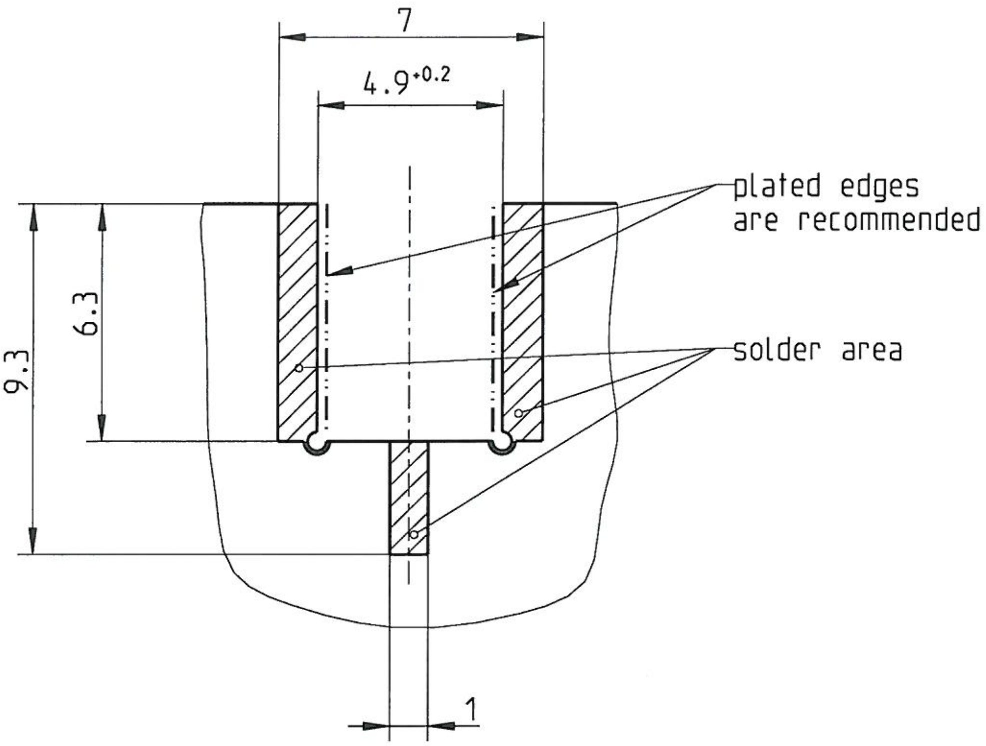
Leiterplatten-Layout
PCB layout
B 173



A wide variety of transmissionline topologies and pcb-parameters like permittivity, substrate thickness, and board-stackup are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector.
Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommendation for optimum solderability of the connector.
In order to guarantee optimum high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.

Formblatt: TCC_FB_05_PE_A4_Einzelteil Pfad: I:\Proe-config\Rahmen\ Datei: A4_EINZELTEIL_EDB.FRM Version: 1.0

Rosenberger Hochfrequenztechnik 84526 Tittmoning Pro/ENGINEER	general tolerance ISO 2768 m-H	RN 006-01 dimensions <0,5 and symmetry	scale: 5:1	weight[g]: surface[mm²]:		
			material:			
		date / name	title: Leiterplatten-Layout *PCB layout*			
	drawn	24.07.2003 A_Nobis				
	check.	30.11.05 (signature)				
	appr.	2/12/05 (signature)				
	dimensioning incl. finish		part-no..: MB_173		sheet: 1	
b00 05-0615 A_Nobis 15.11.2005					of: 1	
a00 03-0485 A_Nobis 24.07.2003	distribution to:	FE X / AZ . / QSM . / RMT . / . .	remarks: .			
rev. change-no name date						

-METRIC-
ISO-Projektion Methode E